FUXINSEMI
INNOVATOR IN SEMICONDUCTOR

BC817-16/25/40

General Purpose Transistors
NPN Silicon

FEATURES

- Ldeally suited for automatic insertion
- Epitaxial planar die construction
- Complementary PNP type available(BC807)

SOT-23

MAXIMUM RATINGS (T_a=25℃ unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{CBO}	Collector-Base Voltage	50	V
V_{CEO}	Collector-Emitter Voltage	45	V
V_{EBO}	Emitter-Base Voltage	5	V
I_C	Collector Current	500	mA
P_C	Collector Power Dissipation	300	mW
$R_{\Theta JA}$	Thermal Resistance From Junction To Ambient	417	℃/W
T_J,T_{stg}	Operation Junction and Storage Temperature Range	-55～+150	℃

ELECTRICAL CHARACTERISTICS (T_a=25℃ unless otherwise specified)

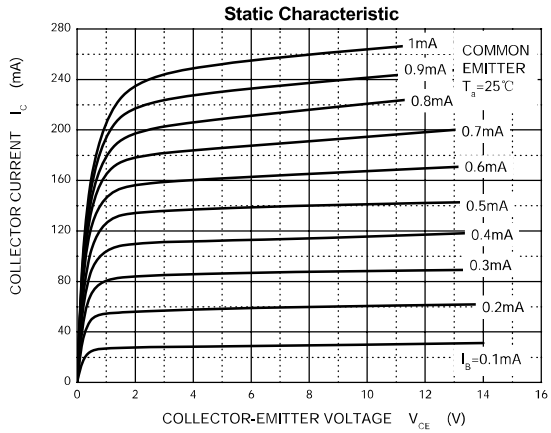
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	V_{CBO}	I_C= 10μA, I_E=0	50			V
Collector-emitter breakdown voltage	V_{CEO}	I_C= 10mA, I_B=0	45			V
Emitter-base breakdown voltage	V_{EBO}	I_E= 1μA, I_C=0	5			V
Collector cut-off current	I_{CBO}	V_{CB}= 45 V , I_E=0			0.1	μA
Emitter cut-off current	I_{EBO}	V_{EB}= 4V, I_C=0			0.1	μA
DC current gain	$h_{FE(1)}$	V_{CE}= 1V, I_C= 100mA	100		600	
	$h_{FE(2)}$	V_{CE}= 1V, I_C= 500mA	40			
Collector-emitter saturation voltage	$V_{CE(sat)}$	I_C= 500mA, I_B= 50mA			0.7	V
Base-emitter saturation voltage	$V_{BE(sat)}$	I_C= 500mA, I_B= 50mA			1.2	V
Base-emitter voltage	V_{BE}	V_{CE}= 1 V, I_C= 500mA			1.2	V
Collecter capactiance	C_{ob}	V_{CB}=10V ,f=1MHz		10		pF
Transition frequency	f_T	V_{CE}= 5 V, I_C= 10mA f=100MHz	100			MHz

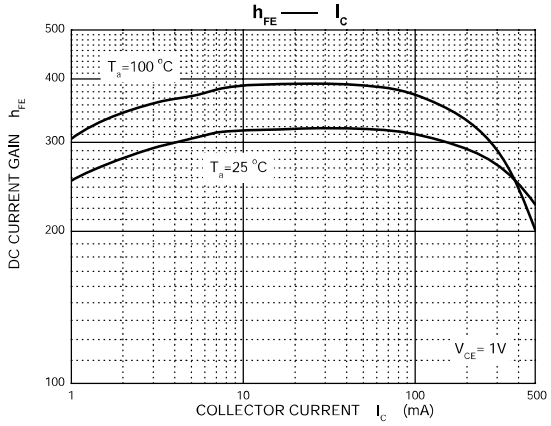
CLASSIFICATION OF $h_{FE\ (1)}$

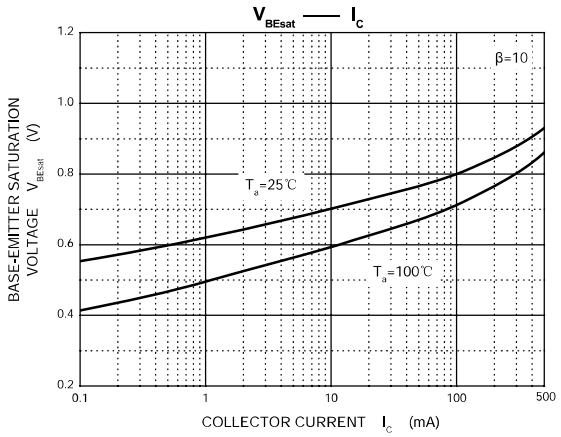
Rank	BC817-16	BC817-25	BC817-40
Range	100-250	160-400	250-600
Marking	6A	6B	6C

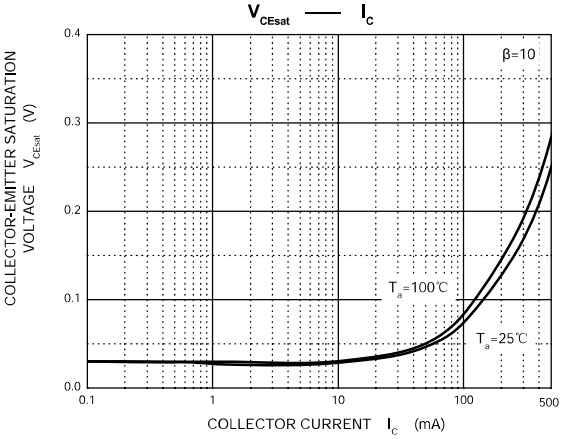
BC817-16/25/40

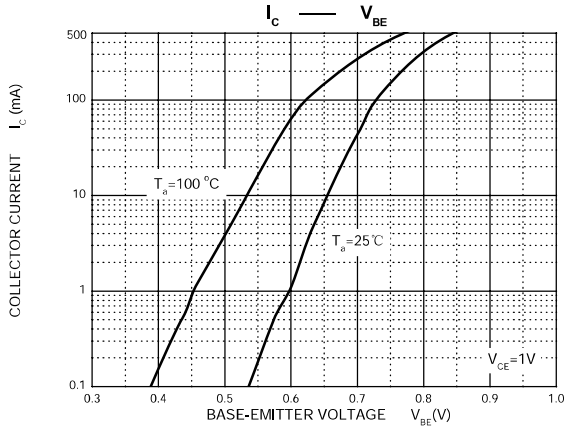
General Purpose Transistors
NPN Silicon

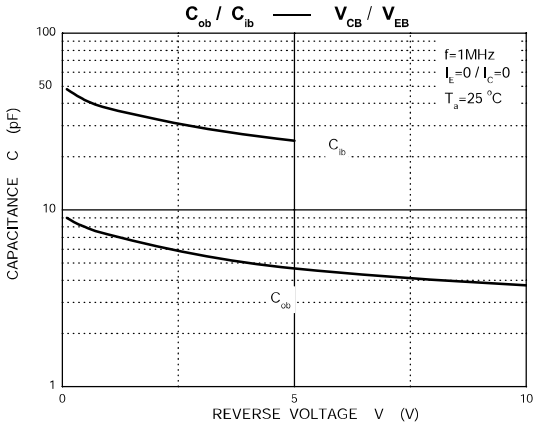


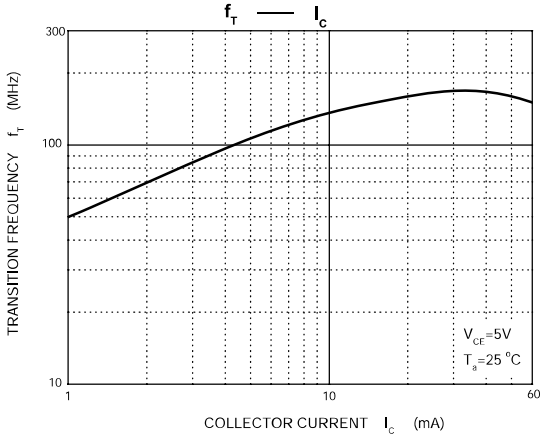


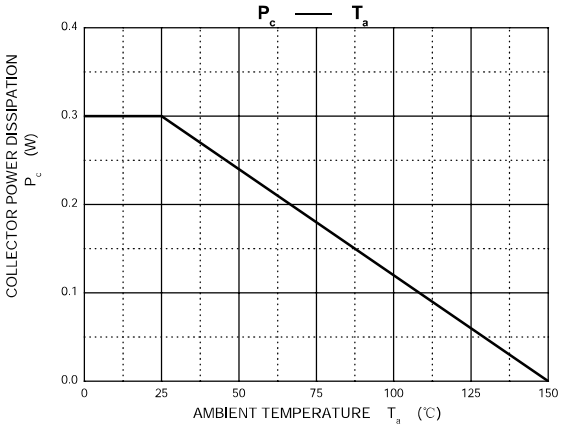




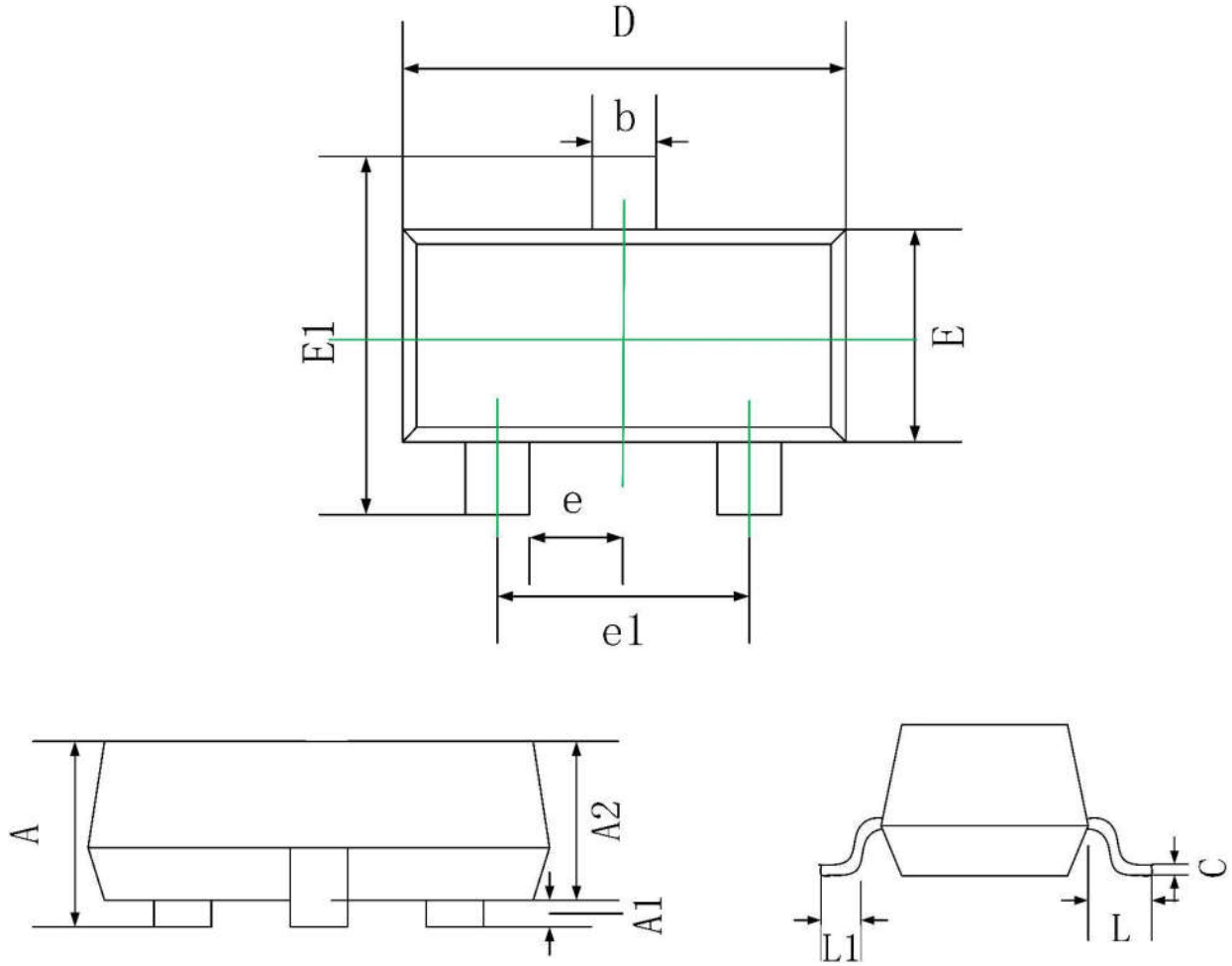








SOT-23 Package Information

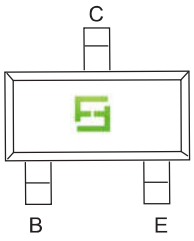
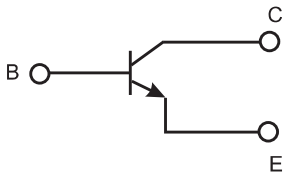


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020

BC817-16/25/40

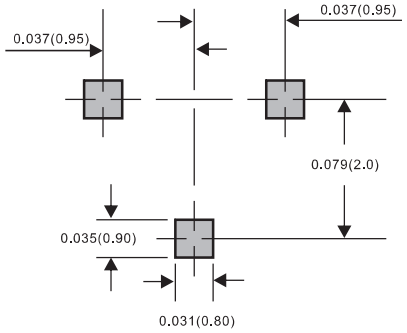
General Purpose Transistors
NPN Silicon

Pinning information

Pin	Simplified outline	Symbol
PinB Base PinC Collector PinE Emitter		

Suggested solder pad layout

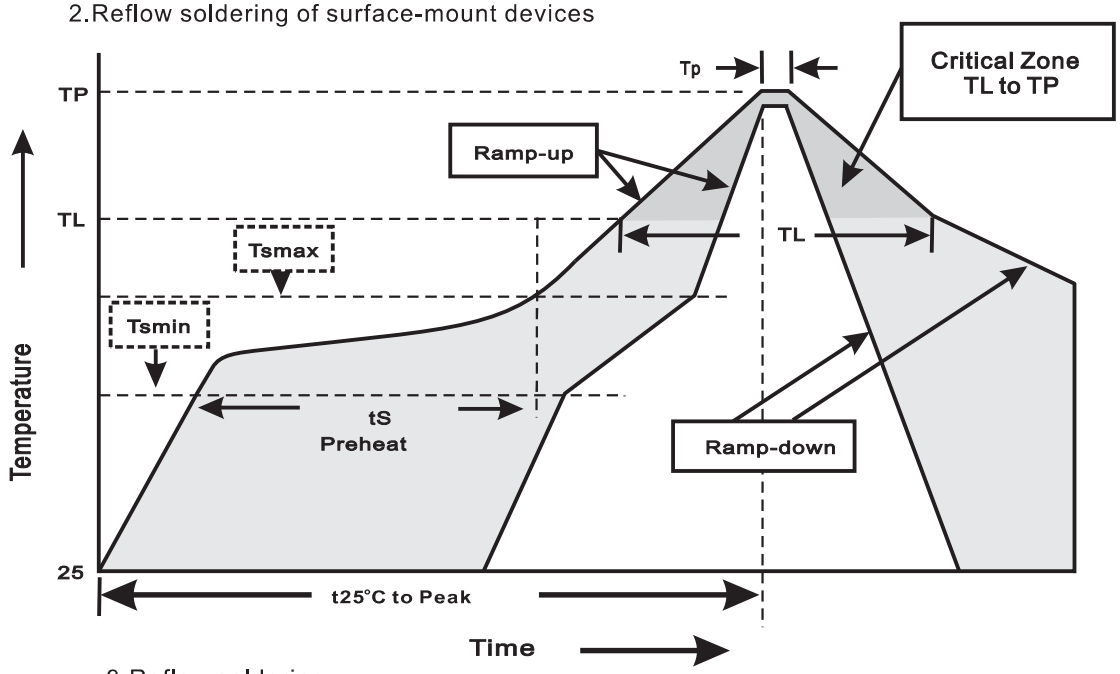
SOT-23



Dimensions in inches and (millimeters)

Suggested thermal profiles for soldering processes

1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(t_s)	 150°C 200°C 60~120sec
Tsmax to T_L -Ramp-upRate	 <3°C/sec
Time maintained above: -Temperature(T_L) -Time(t_L)	 217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Bipolar Transistors - BJT ***category:***

Click to view products by FUXINSEMI ***manufacturer:***

Other Similar products are found below :

619691C MCH4017-TL-H MMBT-2369-TR BC546/116 BC557/116 BSW67A NJVMJD148T4G NTE123AP-10 NTE153MCP NTE16 NTE195A NTE92 C4460 2N4401-A 2N6728 2SA1419T-TD-H 2SA2126-E 2SB1204S-TL-E 2SC2712S-GR,LF 2SC5488A-TL-H 2SD2150T100R SP000011176 2N2907A 2N3904-NS 2N5769 2SC2412KT146S 2SD1816S-TL-E CPH6501-TL-E MCH4021-TL-E MJE340 US6T6TR NJL0281DG 732314D CPH3121-TL-E CPH6021-TL-H 873787E IMZ2AT108 UMX21NTR MCH6102-TL-E NJL0302DG 2N3583 30A02MH-TL-E TN6717A NSV40301MZ4T1G NTE13 NTE26 NTE282 NTE323 NTE350 NTE81